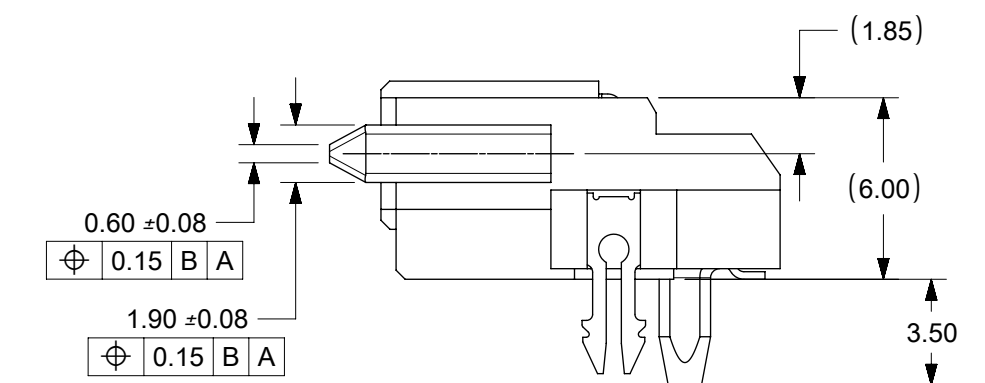


- NOTES:
- MATERIAL
HOUSING: LIQUID CRYSTALLINE POLYMER, GLASS FILLED, UL 94V-0, COLOR: BLACK
TERMINAL: COPPER ALLOY
FORKLOCK: COPPER ALLOY
 - FINISHES:
TERMINAL CONTACT: 0.76µm MIN. SELECTIVE GOLD OVER 1.27µm MIN. NICKEL UNDERPLATE
TERMINAL SOLDER TAIL: 2.54µm MIN. TIN OVER 1.27µm MIN. NICKEL UNDERPLATE
FORKLOCK: 2.54µm MIN. TIN OVER 1.27µm MIN. NICKEL UNDERPLATE
 - PRODUCT SPECIFICATION: PS-78776-001
 - PACKAGING SPECIFICATION : SEE TABLE
 - MOLEX LOGO, SERIES NUMBER, CAVITY ID AND DATE CODE LOCATED APPROXIMATELY AS SHOWN
 - NON FUNCTIONAL CORE HOLE MAY VARY
 - PRODUCT IS COMPLIANT TO RoHS DIRECTIVE WITH THE FOLLOWING BANNED SUBSTANCES - LEAD, MERCURY, CADMIUM, HEXAVALENT CHROMIUM, POLYBROMINATED BIPHENYLS AND POLYBROMINATED DIPHENYL ETHERS.
 - REFER TO AS-78776-001 FOR PCB ROUTING RECOMMENDATIONS.



SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: ADD BLADE OPTION					
	DIMENSION UNITS	SCALE						
▽ = 0	MM	NTS			SAS/PCIE			
▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)				RECEPTACLE, RIGHT-ANGLE SMT, 4.15MM HEIGHT			
▽ = 0	ANGULAR TOL ± 3.0°				PRODUCT CUSTOMER DRAWING			
▽ = 0	4 PLACES	±	EC NO: 617293	2018/02/23	DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
▽ = 0	3 PLACES	±	DRWN: KUCHILA	2019/06/26	SD-78776-001	PSD	001	A
▽ = 0	2 PLACES	± 0.2	CHK'D: SHONG	2019/06/26				
▽ = 0	1 PLACE	±	APPR: SHONG	2019/06/26	INITIAL REVISION:			
▽ = 0	0 PLACES	±	DRWN: CGOH	2012/06/25	MATERIAL NUMBER	CUSTOMER		SHEET NUMBER
▽ = 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER
▽ = 0				A3-SIZE	78776	SEE TABLE	IBM	1 OF 3

